

09/993615

Abstract of Disclosure

To enable a probe to be applied to a probe card for use in inspecting the IC chip having a fine pitch such as 100 μ m, for example, as a pitch size between the electrodes by improving the probe for the probe card having a bare wire structure made of palladium alloy and the probe for the probe card having a bare wire structure made of beryllium copper alloy. There is provided a probe for the probe card characterized in that the same is comprised of a structure where either nickel plating or nickel alloy plating is applied to the surface of the core material made of either palladium alloy or beryllium copper alloy. In addition, there is provided a probe for the probe card having a structure where either nickel plating or nickel alloy plating is applied to the surface of the core material made of either palladium alloy or beryllium copper alloy and further the wire drawing with the wire drawing dies is applied to it.